

OL-NX5P2924B

wafer level chip-scale package; 6 bumps; 0.87 x 1.37 x 0.50 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP6
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-1-2014

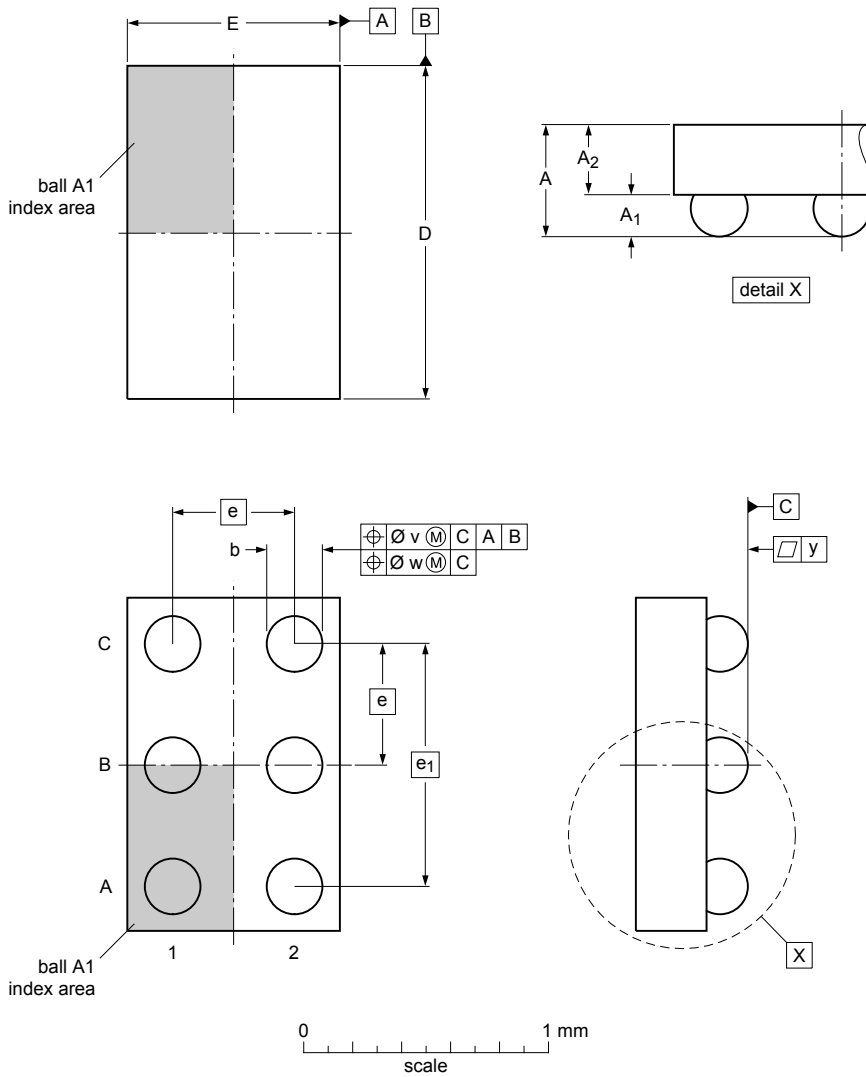
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.34	-	1.37	1.4	mm
E	package width	0.84	-	0.87	0.9	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

WLCSP6: wafer level chip-scale package; 6 bumps; 0.87 x 1.37 x 0.50 mm NX5P2924B



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	v	w	y
max	0.50	0.19	0.315	0.25	1.40	0.90					
nom		0.17	0.285	0.23	1.37	0.87	0.5	1.0	0.05	0.015	0.03
min		0.15	0.255	0.21	1.34	0.84					

wlcspp6_nx5p2924b_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX5P2924B					-13-07-08- 14-01-21

Fig. 1. Package outline WLCSP6 (OL-NX5P2924B)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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Date of release: 8 February 2016
